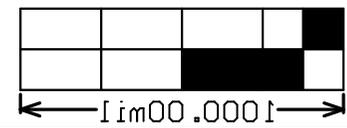
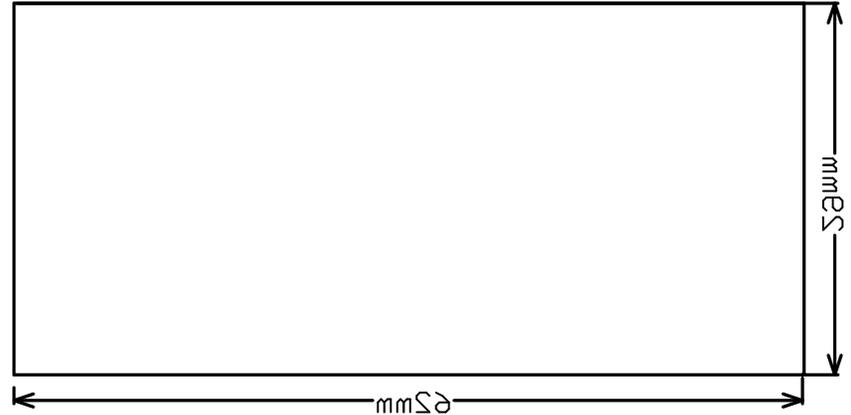


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30165	REV: A	SUN REV: Not In VersionControl
M2 Board Dimensions	TID #: ChangeMe!		
PLOT NAME = Assembly Top	GENERATED : 11/15/2016 2:10:49 PM	TEXAS INSTRUMENTS	



PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP30165	REV: A	SUN REV: Not In VersionControl
	TID #: ChangeMe!	MS Board Dimensions	
PLOT NAME = Assembly Bottom	GENERATED : 11/15/2016 2:10:49 PM	TEXAS INSTRUMENTS	

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